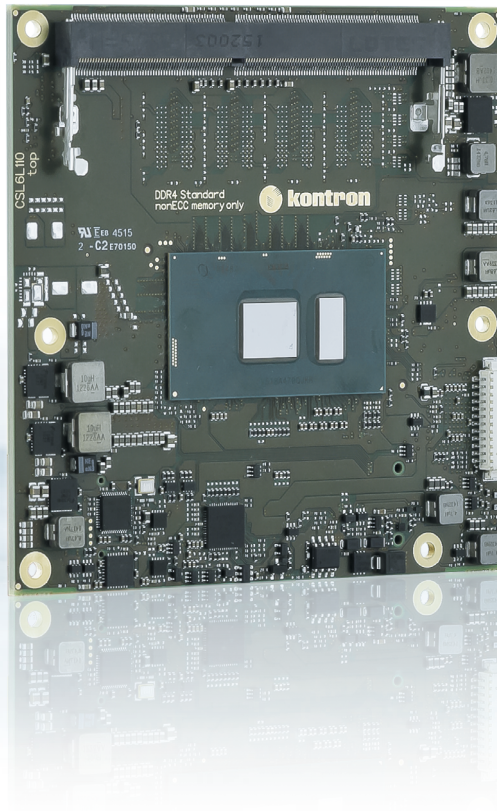


COMe-cSL6



COM Express® basic Type 6 with 6th Gen Intel® Core™ processors

- ▶ COM Express compact pin-out type 6 Computer-on-Module with 6th Gen Intel® Core™ processors
- ▶ Up to 24 GByte DDR4 memory (8 GByte DDR4 memory down)
- ▶ Up to 10 lanes PCIe 3.0
- ▶ 4x USB 3.0, 2x SATA 6G

POSSIBILITIES START HERE



▶ TECHNICAL INFORMATION

| | |
|--------------------------|--|
| COMPLIANCE | COM Express Compact Pin-out Type 6 |
| DIMENSIONS (H x W x D) | 95 x 95 mm |
| CPU | Intel® Core™ i7-6600U (2x 2.60 GHz, GT3, 15 W) Intel® Core™ i5-6300U (2x 2.40 GHz, GT3, 15 W) Intel® Core™ i3-6100U (2x 2.30 GHz, GT2, 15 W) Intel® Celeron® Processor 3955U |
| CHIPSET | Integrated SoC |
| MAIN MEMORY | 1x DDR4 SO-DIMM up to 16 GByte, 2nd channel DDR4- memory down up to 8 GByte |
| GRAPHICS CONTROLLER | Intel® HD Graphics 520 |
| ETHERNET CONTROLLER | Intel® I219LM |
| ETHERNET | 10/100/1000 MBit Ethernet |
| HARD DISK | 2x SATA 6Gb/s |
| FLASH ONBOARD | up to 32 GByte SLC eMMC (depending on SKU - standard feature or available on request) |
| PCI Express/ PCI SUPPORT | 5x PCIe3.0 on PCIe lane 0-4 (3.0 only i5/ i7 SKUs) 5 controllers, 5 x1, 1 x4 + 1x 1 Option: 6 Lanes if no LAN 4x PCIe3.0 on PEG Lanes 0-3 (3.0 only i5/ i7 SKUs) 1 Controller, 1 x4 or 1 x2 or 1 x1, (Intel® RST) |
| PANEL SIGNAL | DDI1: DP++, DDI2: DP++, DDI3: -, VGA: -, LVDS: Dual Channel 18/24 bit |
| USB | 4x USB 3.0 (incl. USB 2.0) + 4x USB 2.0 |
| SERIAL | 2x serial interface (RX/TX only) |
| AUDIO | Intel® High Definition Audio |
| COMMON FEATURES | SPI, LPC, SMB, Fast I ² C, Staged Watchdog, RTC, MARS |
| BIOS | AMI Aptio V |
| HUMIDITY | 93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78) |
| ON REQUEST | vPRO (AMT/TXT/AES Support), eDP instead of LVDS, 1x PCIe x1 additional w/o onboard LAN, max. 32 GByte SLC eMMC, industrial grade -40 °C to +85 °C, Security Chip |
| POWER MANAGEMENT | ACPI 6.0, S5 Eco |
| POWER SUPPLY | 8.5 V – 20 V Wide Range ATX, Single Supply Power |
| SPECIAL FEATURES | POSCAP capacitors, Trusted Platform Module TPM 2.0 |
| OPERATING SYSTEMS | Windows® 10, Windows® 8.1, Windows® 7, WES7, Linux, VxWorks |
| TEMPERATURE | Commercial temperature: 0 °C to +60 °C operating, -30 °C to +85 °C non-operating Extended temperature: -25 °C to +75 °C operating, -30 °C to +85 °C non-operating |
| SUPPORTED MODULES | COMe-cSL6 xx-xxxxx |